

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MARTIN EBERHARD	10/12/2017
RECEIVING PARTY DATA	
Name:	INEVIT, INC.
Street Address:	541 JEFFERSON STREET
City:	REDWOOD CITY
State/Country:	CALIFORNIA
Postal Code:	94063
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15491706
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	INEV-160001U1
NAME OF SUBMITTER:	SAMANTHA PITTENGER
SIGNATURE:	/Samantha Pittenger/
DATE SIGNED:	10/12/2017
Total Attachments: 4	
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ASSIGNMENT

WHEREAS, I,

1. **Martin Eberhard**, a citizen of the United States, having a mailing address located at 541 Jefferson Street, Redwood City, CA 94063 and a resident of Woodside, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to:

1. **CAR FLOOR SYSTEM WITH INTEGRATED BATTERY MODULES**
2. **CAR FLOOR SYSTEM WITH INTEGRATED BATTERY MODULES**
3. **CAR FLOOR SYSTEM WITH INTEGRATED BATTERY MODULES**
4. **MODULE HOUSING MANUFACTURING BY DEFORMED METALS**
5. **BATTERY MODULE MOUNTING AREA OF AN ENERGY STORAGE SYSTEM**
6. **BATTERY MODULE COMPARTMENT AND BATTERY MODULE ARRANGEMENT OF AN ENERGY STORAGE SYSTEM**
7. **BATTERY MODULE COMPARTMENT CHAMBER AND BATTERY MODULE MOUNTING AREA OF AN ENERGY STORAGE SYSTEM AND METHOD THEREOF**
8. **MULTI-LAYER CONTACT PLATE CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO BATTERY CELLS IN A BATTERY MODULE**
9. **CONTACT PLATE CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO BATTERY CELLS IN A BATTERY MODULE**
10. **CENTER CONTACT PLATE CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO DIFFERENT GROUPS OF BATTERY CELLS IN A BATTERY MODULE**
11. **CONTACT PLATE INCLUDING AT LEAST ONE BONDING CONNECTOR CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO TERMINALS OF AT LEAST ONE GROUP OF BATTERY CELLS IN A BATTERY MODULE**
12. **HYBRID CONTACT PLATE ARRANGEMENT CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO BATTERY CELLS IN A BATTERY MODULE**
13. **CONTACT PLATE INCLUDING AT LEAST ONE HIGHER-FUSE BONDING CONNECTOR FOR ARC PROTECTION**
14. **METHODS OF WELDING A BONDING CONNECTOR OF A CONTACT PLATE TO A BATTERY CELL TERMINAL**
15. **BATTERY JUNCTION BOX HOUSING CONFIGURED TO DIRECT CRASH FORCES IN AN ELECTRIC VEHICLE**

(collectively the “**INVENTIONS**”) for which I have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Inevit, Inc. (hereinafter “**ASSIGNEE**”), a California corporation, having a place of business at 541 Jefferson Street, Redwood City, California 94063, U.S.A., desires to

acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to:

Case No.	App. No.	Filing Date	Title
INEV-000CP1	62/408,445	14-Oct-2016	CAR FLOOR SYSTEM WITH INTEGRATED BATTERY MODULES
INEV-000CP2	62/414,208	28-Oct-2016	CAR FLOOR SYSTEM WITH INTEGRATED BATTERY MODULES
INEV-000CP3	62/422,090	15-Nov-2016	CAR FLOOR SYSTEM WITH INTEGRATED BATTERY MODULES
INEV-000NP1	62/422,111	15-Nov-2016	MODULE HOUSING MANUFACTURING BY DEFORMED METALS
INEV-160001U1	15/491,706	19-Apr-2017	BATTERY MODULE MOUNTING AREA OF AN ENERGY STORAGE SYSTEM
INEV-160001U2	15/491,749	19-Apr-2017	BATTERY MODULE COMPARTMENT AND BATTERY MODULE ARRANGEMENT OF AN ENERGY STORAGE SYSTEM
INEV-160001U3	15/491,767	19-Apr-2017	BATTERY MODULE COMPARTMENT CHAMBER AND BATTERY MODULE MOUNTING AREA OF AN ENERGY STORAGE SYSTEM AND METHOD THEREOF
INEV-160002U1	15/641,710	5-Jul-2017	MULTI-LAYER CONTACT PLATE CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO BATTERY CELLS IN A BATTERY MODULE
INEV-160002U2	15/641,762	5-Jul-2017	CONTACT PLATE CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO BATTERY CELLS IN A BATTERY MODULE
INEV-160002U3	15/641,786	5-Jul-2017	CENTER CONTACT PLATE CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO DIFFERENT GROUPS OF BATTERY CELLS IN A BATTERY MODULE
INEV-160002U4	15/641,815	5-Jul-2017	CONTACT PLATE INCLUDING AT LEAST ONE BONDING CONNECTOR CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO TERMINALS OF AT LEAST ONE GROUP OF BATTERY CELLS IN A BATTERY MODULE

INEV-160002U5	15/641,836	5-Jul-2017	HYBRID CONTACT PLATE ARRANGEMENT CONFIGURED TO ESTABLISH ELECTRICAL BONDS TO BATTERY CELLS IN A BATTERY MODULE
INEV-160002U6	15/641,864	5-Jul-2017	CONTACT PLATE INCLUDING AT LEAST ONE HIGHER-FUSE BONDING CONNECTOR FOR ARC PROTECTION
INEV-160004	15/641,910	5-Jul-2017	METHODS OF WELDING A BONDING CONNECTOR OF A CONTACT PLATE TO A BATTERY CELL TERMINAL
INEV-160007	15/677,373	15-Aug-2017	BATTERY JUNCTION BOX HOUSING CONFIGURED TO DIRECT CRASH FORCES IN AN ELECTRIC VEHICLE

, and I do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages

Ref. Nos. INEV-000CP1, INEV-000CP2, INEV-000CP3, INEV-000NP1, INEV-160001U1, INEV-160001U2, INEV-160001U3, INEV-160002U1, INEV-160002U2, INEV-160002U3, INEV-160002U4, INEV-160002U5, INEV-160002U6, INEV-160004, INEV-160007

and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Waukesha, CA, on 12 OCT 2017
LOCATION DATE



Martin Eberhard